

bq24715 2-3 节窄电压直流 (NVDC)-1 电池充电器控制器 具有超快速瞬态响应和高轻负载效率

1 特性

- 6-24V 输入系统管理总线 (SMBus) NVDC-1 2-3S 电池充电器控制器
- 无电池或深度放电电池工作时系统瞬时接通运行
- 100 μ s 的超快速瞬态响应
- 500 μ A 的超低静态电流, 以及 20mA 负载时高脉冲频率调制 (PFM) 轻负载效率, 以符合能源之星 (Energy Star) 和能源相关产品 (ErP) Lot6 规范
- 开关频率: 600kHz/800kHz/1MHz
- 具有高精度的可编程系统/充电电压 (每步长 16mV), 输入/充电电流 (每步长 64mA)
 - 充电电压稳压范围为 $\pm 0.5\%$
 - $\pm 3\%$ 输入/充电电流调节
 - $\pm 2\%$ 40x 输入 / 16x 充电电流监控输出
- 支持电池 LEARN (学习) 功能
- 在深度放电电池或无电池时最大限度地提高 CPU 性能
- 集成 NMOS ACFET 和 RBFET 驱动器
- 20 引脚 3.5mm x 3.5mm² 四方扁平无引线 (QFN) Package

2 应用范围

- Ultrabook, 笔记本电脑和平板个人电脑
- 工业用和医疗用设备
- 便携式设备

3 说明

bq24715 是一款 NVDC-1 同步电池充电控制器, 此充电器具有针对 2S 或 3S 锂离子电池充电应用的低静态电流、高轻负载效率, 从而提供低组件数量。

电源路径管理可实现系统在电池电压上的电压调节, 但是不会下降到低于可编程系统最低电压以下。

bq24715 提供针对电源路径管理的 N 通道 ACFET 和 RBFET 驱动器。它还提供外部 P 通道电池 FET 的驱动器。环路补偿是完全集成的。

bq24715 通过 SMBus 通信接口提供具有极高稳压精度的可编程 11 位充电电压, 7 位输入/充电电流和 6 位最低系统电压。

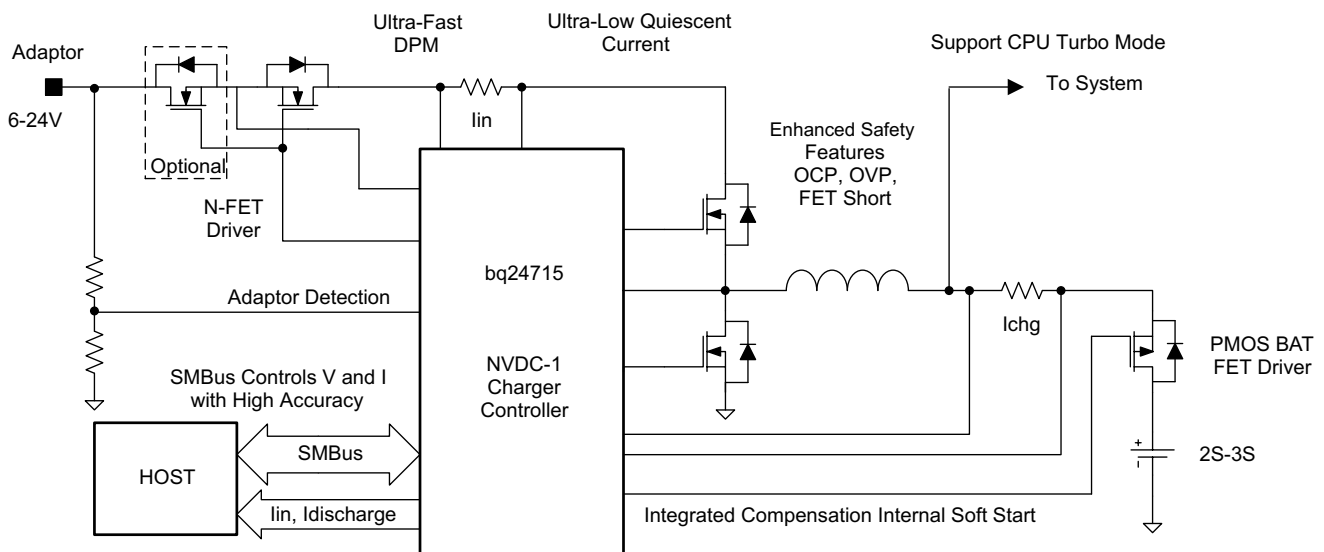
bq24715 通过 IOUT 引脚监控适配器电流或电池放电电流, 从而使主机能够在需要时减低 CPU 速度。

bq24715 提供针对过流、过压和 MOSFET 短路的广泛安全特性。

器件信息

器件名称	封装 (引脚)	封装尺寸
bq24715	超薄四方扁平无引线封装 (VQFN) (20)	3.5mm x 3.5mm

Simplified Application Diagram



4 修订历史记录

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Original (March 2013) to Revision A

Page

-
- 已添加 器件型号至标题，并已按照全新的数据表模板添加器件信息表 1
-

要获得完整数据表，请通过 [电子邮件](#) 与 TI 联系。

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
BQ24715RGRR	ACTIVE	VQFN	RGR	20	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR		BQ715	Samples
BQ24715RGRT	ACTIVE	VQFN	RGR	20	250	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR		BQ715	Samples
HPA02277RGRR	ACTIVE	VQFN	RGR	20	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR		BQ715	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ24715RGRR	VQFN	RGR	20	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q2
BQ24715RGRT	VQFN	RGR	20	250	180.0	12.4	3.75	3.75	1.15	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS

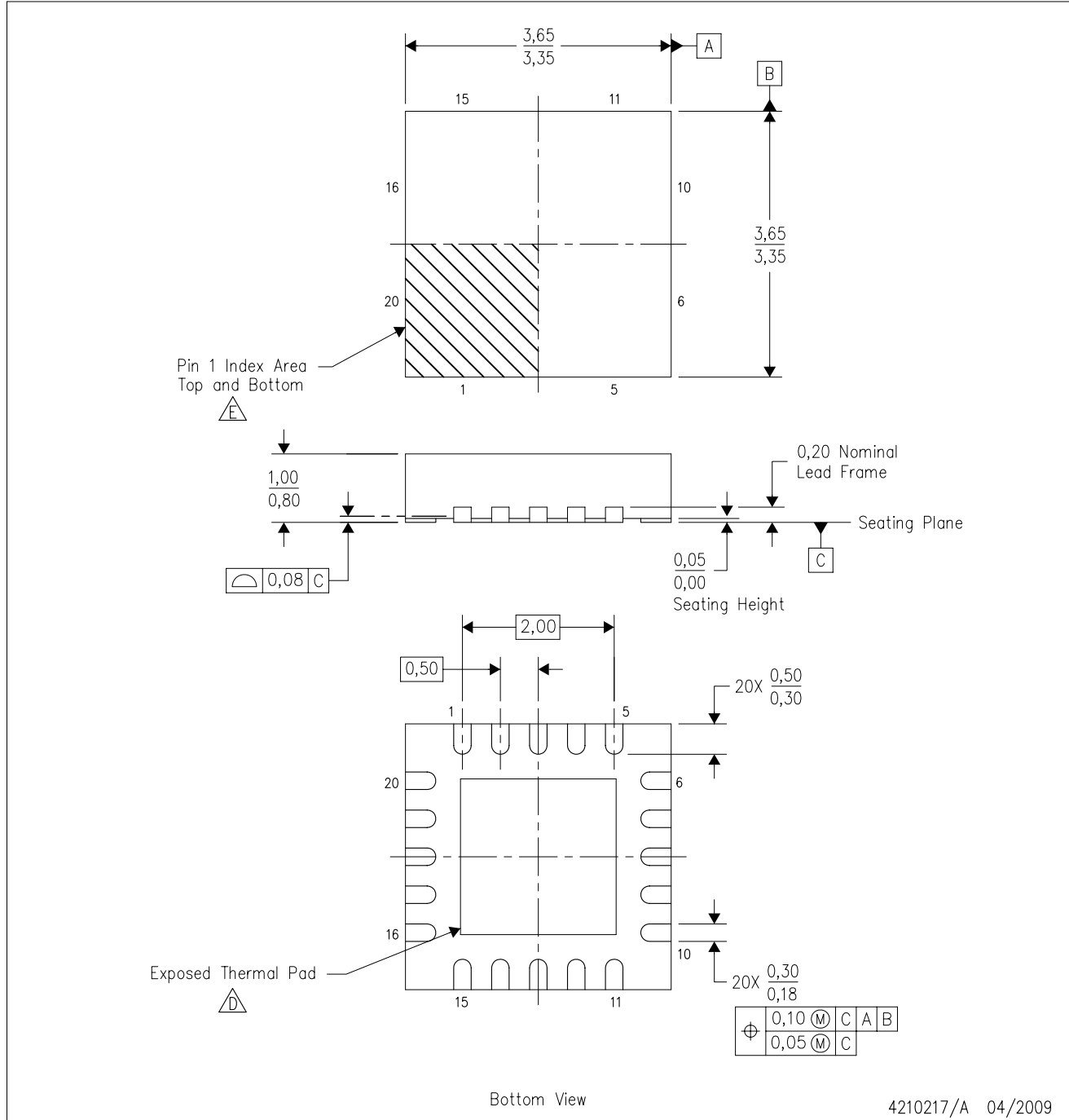


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ24715RGRR	VQFN	RGR	20	3000	367.0	367.0	35.0
BQ24715RGRT	VQFN	RGR	20	250	210.0	185.0	35.0

RGR (S-PVQFN-N20)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
 - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.

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